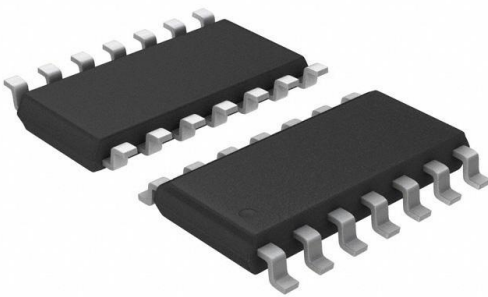


SN74LVC06AMDREP Datasheet

www.digi-electronics.com



SN74LVC06AMDREP

<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	SN74LVC06AMDREP-DG
Manufacturer	Texas Instruments
Manufacturer Product Number	SN74LVC06AMDREP
Description	IC INVERTER 6CH 1-INP 14SOIC
Detailed Description	Inverter IC 6 Channel Open Drain 14-SOIC



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

SN74LVC06AMDREP

Series:

74LVC

Logic Type:

Inverter

Number of Inputs:

1

Voltage - Supply:

1.65V ~ 3.6V

Current - Output High, Low:

-, 24mA

Input Logic Level - High:

1.7V ~ 2V

Operating Temperature:

-55°C ~ 125°C

Supplier Device Package:

14-SOIC

Base Product Number:

74LVC06

Manufacturer:

Texas Instruments

Product Status:

Active

Number of Circuits:

6

Features:

Open Drain

Current - Quiescent (Max):

1 μ A

Input Logic Level - Low:

0.7V ~ 0.8V

Max Propagation Delay @ V, Max CL:

3.5ns @ 3.3V, 50pF

Mounting Type:

Surface Mount

Package / Case:

14-SOIC (0.154", 3.90mm Width)

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

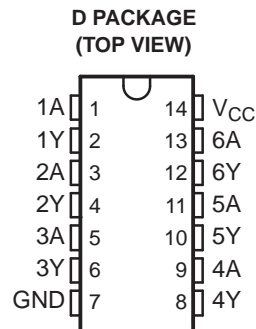
ECCN:

EAR99

FEATURES

- **Controlled Baseline**
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- **Extended Temperature Performance of -55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree ⁽¹⁾**
- **Operates From 1.65 V to 3.6 V**
- **Inputs and Open Drain Outputs Accept Voltages up to 5.5 V**
- **Max t_{pd} of 3.7 ns at 3.3 V**
- **I_{off} Supports Partial Power Down Mode Operation**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



DESCRIPTION/ORDERING INFORMATION

The SN74LVC06A is a hex inverter buffer/driver that is designed for 1.65-V to 3.6-V V_{CC} operation.

The outputs of the SN74LVC06A device are open drain and can be connected to other open-drain outputs to implement active low wired OR or active high wired AND functions. The maximum sink current is 24 mA.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V system environment.

This device is fully specified for partial power down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**FUNCTION TABLE
(EACH INVERTER)**

INPUT A	OUTPUT Y
H	L
L	H



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74LVC06A-EP HEX INVERTER BUFFER/DRIVER WITH OPEN DRAIN OUTPUTS

SCAS832A—APRIL 2007—REVISED MAY 2007

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SOIC – D	Reel of 2500	SN74LVC06AMDREP	LVC06AM

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
V _{CC} Supply voltage range	-0.5	6.5	V
V _I Input voltage range ⁽²⁾	-0.5	6.5	V
V _O Output voltage range	-0.5	6.5	V
I _{IK} Input clamp current	V _I < 0 V	-50	mA
I _{OK} Output clamp current	V _O < 0 V	-50	mA
I _O Continuous output current		±50	mA
Continuous current through V _{CC} or GND		±100	mA
θ _{JA} Package thermal impedance ⁽³⁾		86	°C/W
T _{stg} Storage temperature range	-65	150	°C
P _{tot} Power dissipation ⁽⁴⁾	T _A = -55°C to 125°C	500	mW

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) Above 70°C the value of P_{tot} derates linearly with 8 mW/K.

Recommended Operating Conditions⁽¹⁾

		T _A = 25°C		-55°C to 125°C		UNIT
		MIN	MAX	MIN	MAX	
V _{CC} Supply voltage	Operating	1.65	3.6	1.65	3.6	V
	Data retention only	1.5		1.5		
V _{IH} High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		0.65 × V _{CC}		V
	V _{CC} = 2.3 V to 2.7 V	1.7		1.7		
	V _{CC} = 2.7 V to 3.6 V	2		2		
V _{IL} Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		0.35 × V _{CC}		V
	V _{CC} = 2.3 V to 2.7 V	0.7		0.7		
	V _{CC} = 2.7 V to 3.6 V	0.8		0.8		
V _I Input voltage		0	5.5	0	5.5	V
V _O Output voltage		0	5.5	0	5.5	V

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Recommended Operating Conditions (continued)

		T _A = 25°C		–55°C to 125°C		UNIT	
		MIN	MAX	MIN	MAX		
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		4		mA
		V _{CC} = 2.3 V	8		8		
		V _{CC} = 2.7 V	12		12		
		V _{CC} = 3 V	24		24		

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–55°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V	0.1			0.3		V
	I _{OL} = 4 mA	1.65 V	0.24			0.6		
	I _{OL} = 8 mA	2.3 V	0.3			0.75		
	I _{OL} = 12 mA	2.7 V	0.4			0.6		
	I _{OL} = 24 mA	3 V	0.55			0.8		
I _I	V _I = 5.5 V or GND	3.6 V	±1			±20		μA
I _{off}	V _I or V _O = 5.5 V	0 V	±1			±20		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V	1			40		μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V	500			5000		μA
C _I	V _I = V _{CC} or GND	3.3 V	5					pF

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

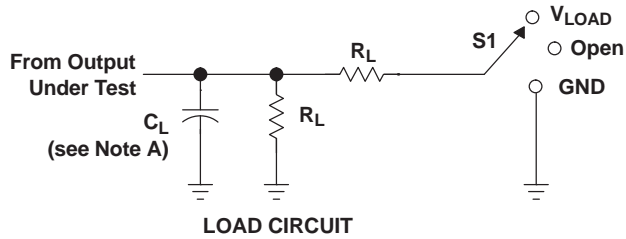
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			–55°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	1.8 V ± 0.15 V	1.4	3	5.1	1.4	7.6	ns
			2.5 V ± 0.2 V	1	1.9	2.8	1	4	
			2.7 V	1	2.4	3.7	1	5	
			3.3 V ± 0.3 V	1	2.2	3.5	1	5	

Operating Characteristics

T_A = 25°C

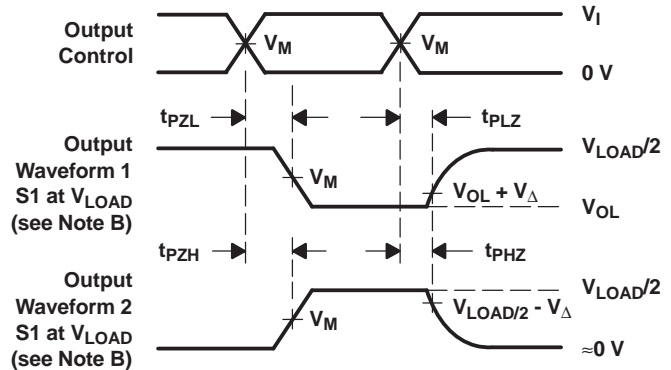
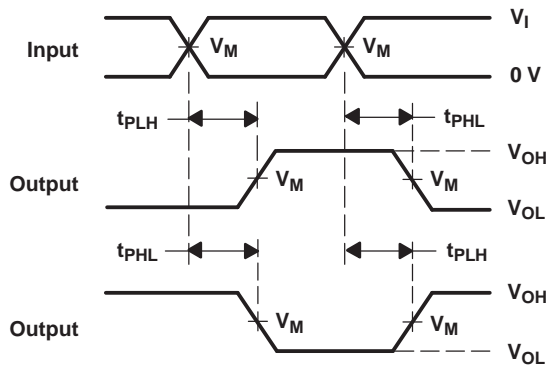
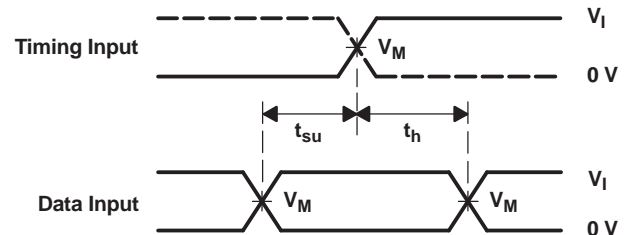
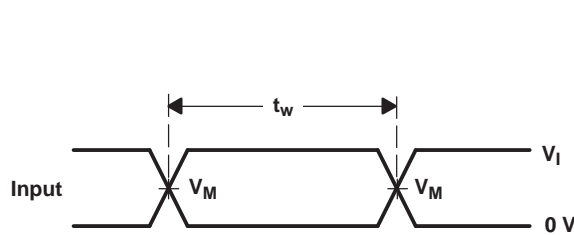
PARAMETER		TEST CONDITIONS	V _{CC}	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	f = 10 MHz	1.8 V	2.1	pF
			2.5 V	2.3	
			3.3 V	2.5	

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pZL} (see Notes E and F)	V_{LOAD}
t_{pLZ} (see Notes E and G)	V_{LOAD}
t_{PHZ}/t_{PZH}	V_{LOAD}

V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
D. The outputs are measured one at a time, with one transition per measurement.
E. Since this device has open-drain outputs, t_{pLZ} and t_{pZL} are the same as t_{pD} .
F. t_{pZL} is measured at V_M .
G. t_{pLZ} is measured at $V_{OL} + V_{\Delta}$.
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LVC06AMDREP	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LC06AM
V62/06661-01XE	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LC06AM

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC06A-EP :

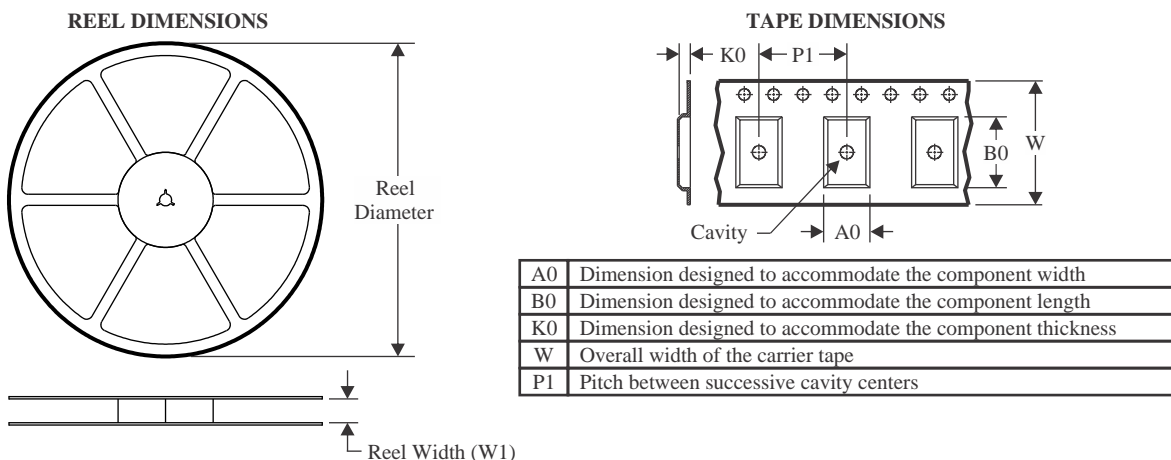
- Catalog : [SN74LVC06A](#)

- Automotive : [SN74LVC06A-Q1](#)

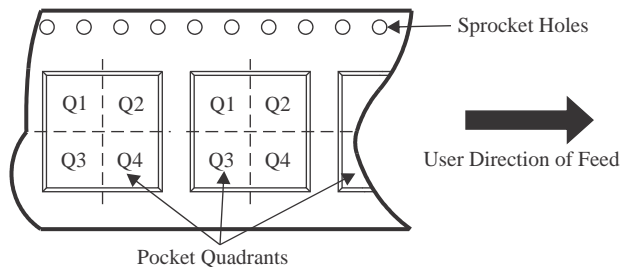
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



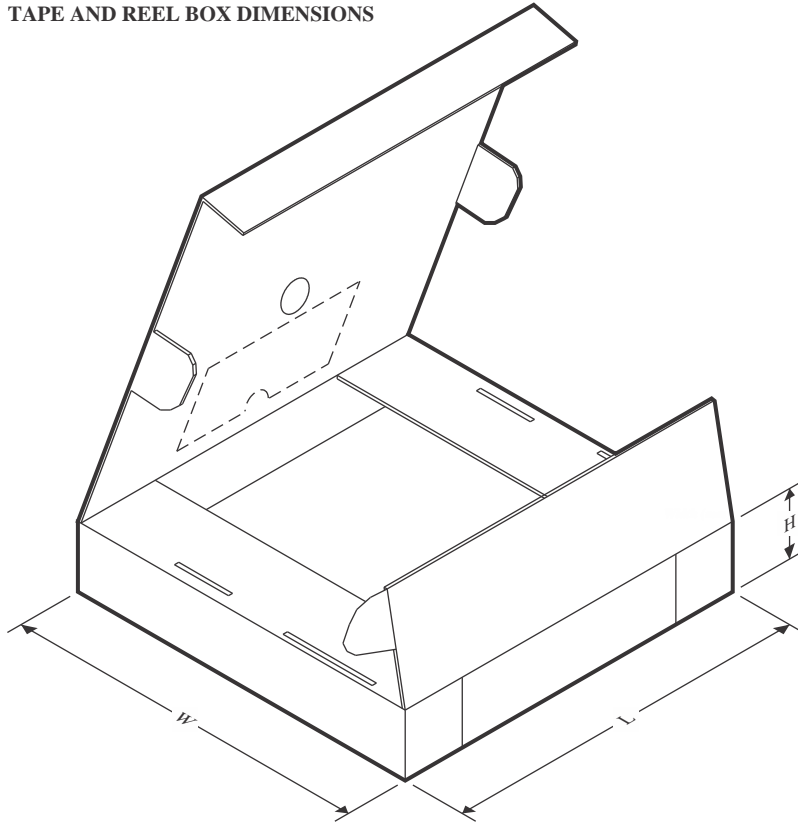
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

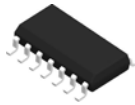
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC06AMDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC06AMDREP	SOIC	D	14	2500	353.0	353.0	32.0

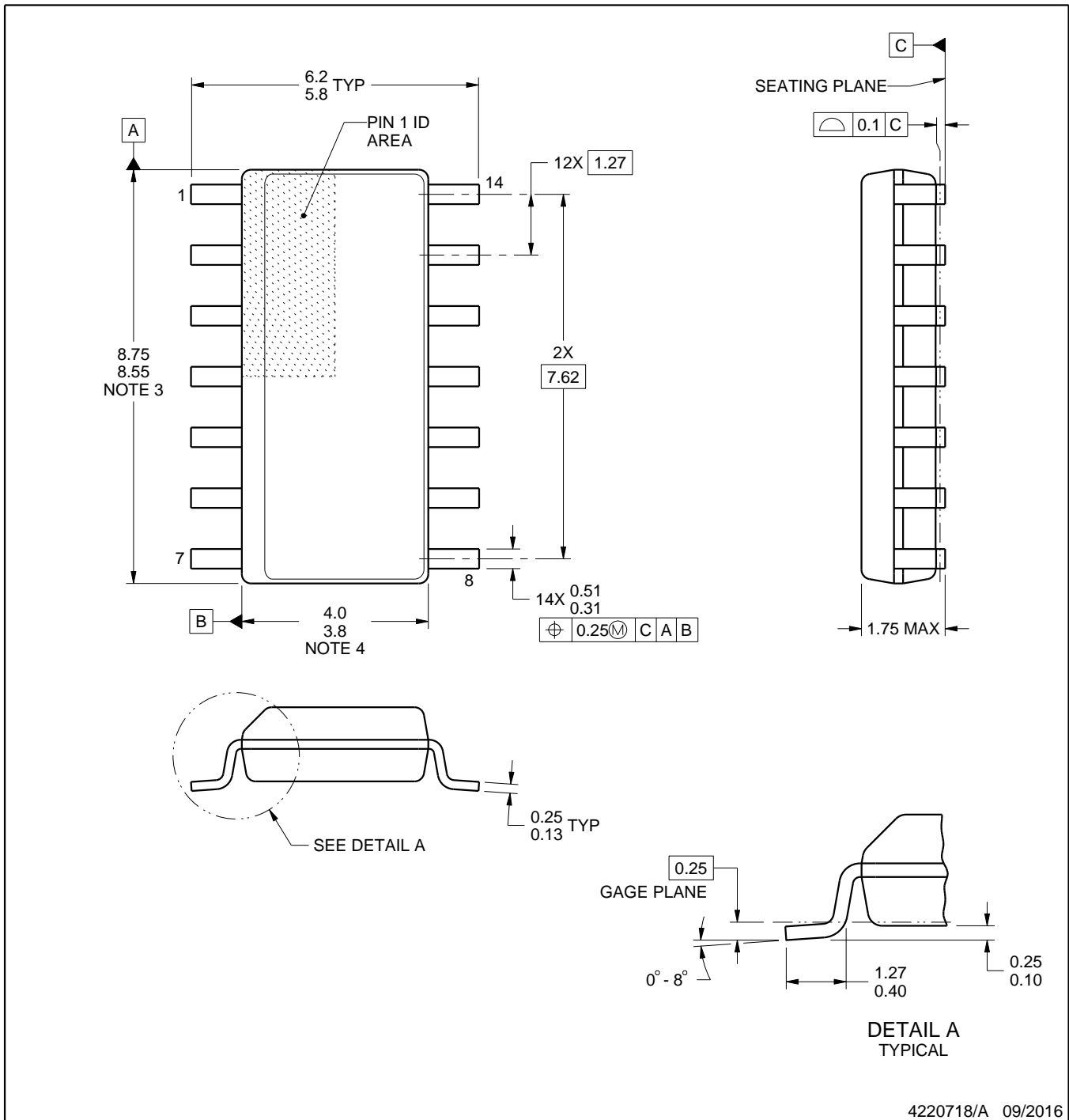


D0014A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

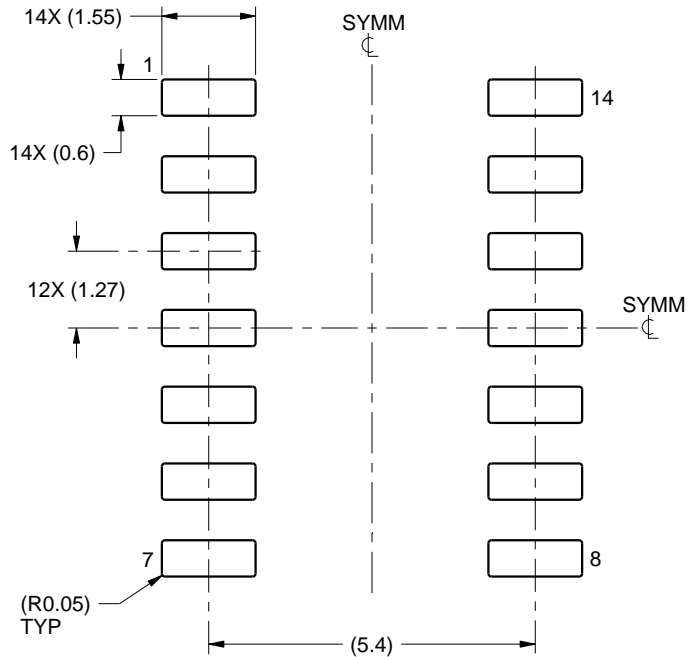
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

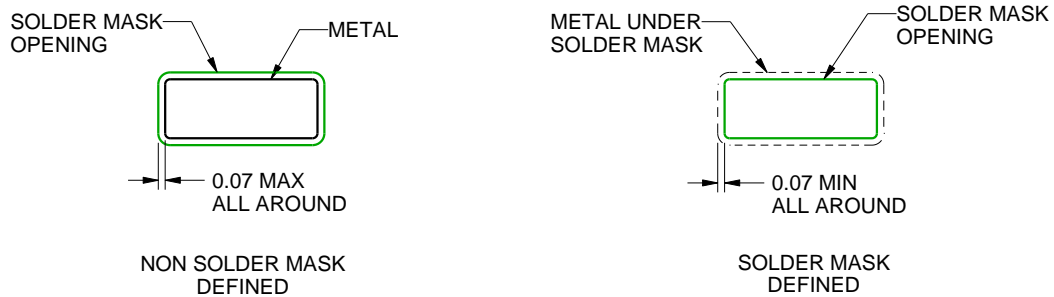
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

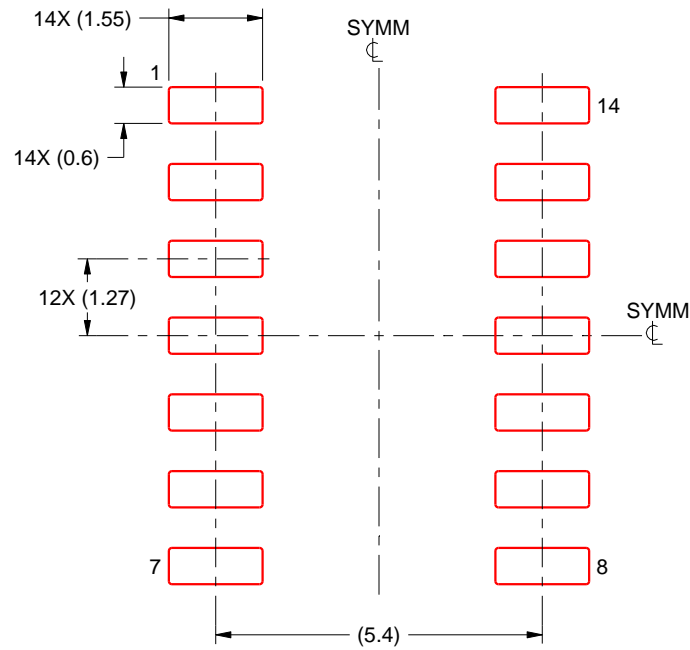
4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN**D0014A****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.